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Specifikacija vmesnika orodja procesne naprave - 503-1. del: Implementacija komunikacije za skupni model objekta - IEC 61784 CP 3/1 in CP 3/2 (IEC/TR 62453-503-1:2009)

Field device tool interface specification -- Part 503-1: Communication implementation for common object model - IEC 61784 CP 3/1 and CP 3/2

Field Device Tool (FDT)-Schnittstellenspezifikation - Teil 503-1: Kommunikationsimplementierung mit dem allgemeinen Objektmodell (COM) - IEC 61784 Kommunikationsprofile (CP) 3/1 und 3/2

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English version

**Field device tool (FDT) interface specification -
Part 503-1: Communication implementation for common object model -
IEC 61784 CP 3/1 and CP 3/2
(IEC/TR 62453-503-1:2009)**

Spécification des interfaces des
outils des dispositifs de terrain (FDT) -
Partie 503-1: Implémentation
des communications
pour le modèle objet commun -
CEI 61784 CP 3/1 et CP 3/2
(CEI/TR 62453-503-1:2009)

Field Device Tool (FDT)-
Schnittstellenspezifikation -
Teil 503-1: Kommunikationsimplementierung
mit dem allgemeinen Objektmodell (COM) -
Kommunikationsprofile (CP) 3/1 und 3/2
nach IEC 61784
(IEC/TR 62453-503-1:2009)

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This Technical Report was approved by CENELEC on 2009-10-01.

CENELEC members are the national electrotechnical committees of Austria, Belgium, Bulgaria, Cyprus, the Czech Republic, Denmark, Estonia, Finland, France, Germany, Greece, Hungary, Iceland, Ireland, Italy, Latvia, Lithuania, Luxembourg, Malta, the Netherlands, Norway, Poland, Portugal, Romania, Slovakia, Slovenia, Spain, Sweden, Switzerland and the United Kingdom.

CENELEC

European Committee for Electrotechnical Standardization
Comité Européen de Normalisation Electrotechnique
Europäisches Komitee für Elektrotechnische Normung

Central Secretariat: Avenue Marnix 17, B - 1000 Brussels

Foreword

The text of document 65E/67/CDV, future edition 1 of IEC/TR 62453-503-1, prepared by SC 65E, Devices and integration in enterprise systems, of IEC TC 65, Industrial-process measurement, control and automation, was submitted to the IEC-CENELEC parallel vote and was approved by CENELEC as CLC/TR 62453-503-1 on 2009-10-01.

This standard is to be used in conjunction with EN 62453-3xy series.

Annex ZA has been added by CENELEC.

Endorsement notice

The text of the Technical Report IEC/TR 62453-503-1:2009 was approved by CENELEC as a Technical Report without any modification.

In the official version, for Bibliography, the following note has to be added for the standard indicated:

IEC 61784-1

NOTE Harmonized as EN 61784-1:2008 (not modified).

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Annex ZA (normative)

Normative references to international publications with their corresponding European publications

The following referenced documents are indispensable for the application of this document. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

NOTE When an international publication has been modified by common modifications, indicated by (mod), the relevant EN/HD applies.

<u>Publication</u>	<u>Year</u>	<u>Title</u>	<u>EN/HD</u>	<u>Year</u>
IEC 61158	series	Industrial communication networks - Fieldbus specifications	EN 61158	series
IEC 62453-1	2009	Field device tool (FDT) interface specification - Part 1: Overview and guidance	EN 62453-1	2009
IEC 62453-2	2009	Field device tool (FDT) interface specification - Part 2: Concepts and detailed description	EN 62453-2	2009
IEC/TR 62453-41	2009	Field device tool (FDT) interface specification - Part 41: Object model integration profile - Common object model	CLC/TR 62453-41	2009
IEC 62453-303-1	2009	Field device tool (FDT) interface specification - Part 303-1: Communication profile integration - IEC 61784 CP 3/1 and CP 3/2	EN 62453-303-1	2009

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TECHNICAL REPORT



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Part 503-1: Communication implementation for common object model –
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INTERNATIONAL ELECTROTECHNICAL COMMISSION

FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –

**Part 503-1: Communication implementation for common object model –
IEC 61784 CP 3/1 and CP 3/2**

FOREWORD

- 1) The International Electrotechnical Commission (IEC) is a worldwide organization for standardization comprising all national electrotechnical committees (IEC National Committees). The object of IEC is to promote international co-operation on all questions concerning standardization in the electrical and electronic fields. To this end and in addition to other activities, IEC publishes International Standards, Technical Specifications, Technical Reports, Publicly Available Specifications (PAS) and Guides (hereafter referred to as "IEC Publication(s)"). Their preparation is entrusted to technical committees; any IEC National Committee interested in the subject dealt with may participate in this preparatory work. International, governmental and non-governmental organizations liaising with the IEC also participate in this preparation. IEC collaborates closely with the International Organization for Standardization (ISO) in accordance with conditions determined by agreement between the two organizations.
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IEC/TR 62453-503-1, which is a technical report, has been prepared by subcommittee 65E: Devices and integration in enterprise systems, of IEC technical committee 65: Industrial-process measurement, control and automation:

This part, in conjunction with the other parts of the first edition of the IEC 62453 series cancels and replaces IEC/PAS 62453-1, IEC/PAS 62453-2, IEC/PAS 62453-3, IEC/PAS 62453-4 and IEC/PAS 62453-5 published in 2006, and constitutes a technical revision.

Each part of the IEC/TR 62453-5xy series is intended to be read in conjunction with its corresponding part in the IEC 62453-3xy series.

The text of this technical report is based on the following documents:

Enquiry draft	Report on voting
65E/67/DTR	65E/116/RVC

Full information on the voting for the approval of this technical report can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

The list of all parts of the IEC 62453 series, under the general title *Field Device Tool (FDT) interface specification*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the maintenance result date indicated on the IEC web site under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

- reconfirmed,
- withdrawn,
- replaced by a revised edition, or
- amended.

A bilingual version of this publication may be issued at a later date.

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IMPORTANT – The “colour inside” logo on the cover page of this publication indicates that it contains colours which are considered to be useful for the correct understanding of its contents. Users should therefore print this publication using a colour printer.

INTRODUCTION

This part of IEC 62453 is an interface specification for developers of FDT (Field Device Tool) components for function control and data access within a client/server architecture. The specification is a result of an analysis and design process to develop standard interfaces to facilitate the development of servers and clients by multiple vendors that need to interoperate seamlessly.

With the integration of fieldbusses into control systems, there are a few other tasks which need to be performed. In addition to fieldbus- and device-specific tools, there is a need to integrate these tools into higher-level system-wide planning- or engineering tools. In particular, for use in extensive and heterogeneous control systems, typically in the area of the process industry, the unambiguous definition of engineering interfaces that are easy to use for all those involved is of great importance.

A device-specific software component, called DTM (Device Type Manager), is supplied by the field device manufacturer with its device. The DTM is integrated into engineering tools via the FDT interfaces defined in this specification. The approach to integration is in general open for all kind of fieldbusses and thus meets the requirements for integrating different kinds of devices into heterogeneous control systems.

Figure 1 shows how IEC/TR 62453-503-1 is aligned in the structure of IEC 62453 series.

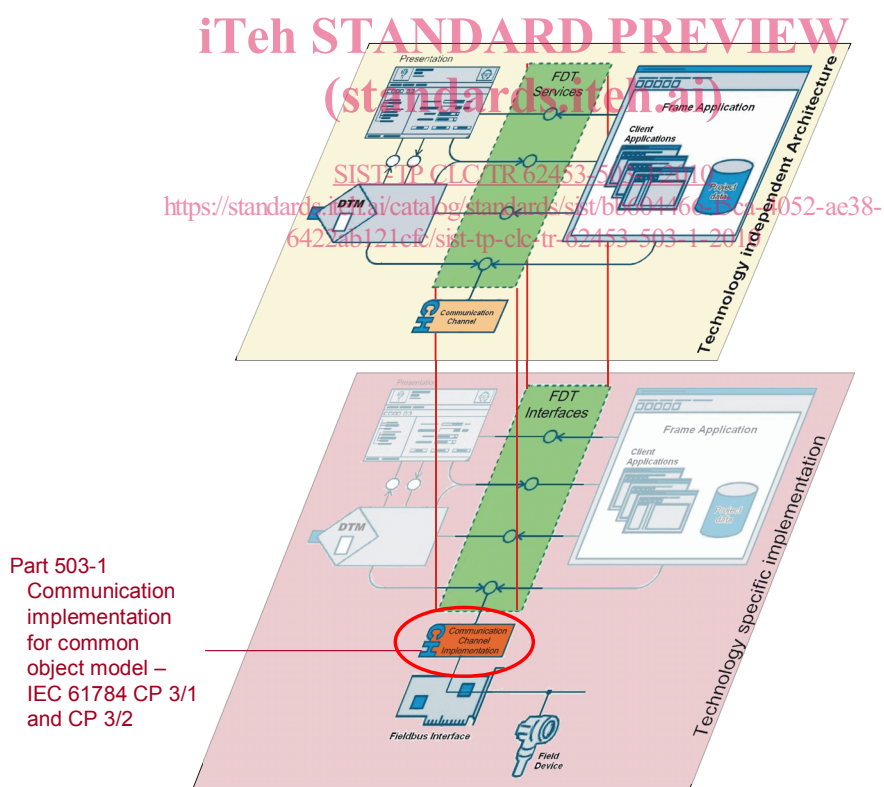


Figure 1 – Part 503-1 of the IEC 62453 series

FIELD DEVICE TOOL (FDT) INTERFACE SPECIFICATION –

Part 503-1: Communication implementation for common object model – IEC 61784 CP 3/1 and CP 3/2

1 Scope

IEC 62435-503-1, which is a technical report, provides information for integrating the PROFIBUS protocol into the FDT interface specification (IEC 62453-2).

This part of IEC 62453 specifies communication and other services.

This specification neither contains the FDT specification nor modifies it.

2 Normative references

The following referenced documents are indispensable for the application of this specification. For dated references, only the edition cited applies. For undated references, the latest edition of the referenced document (including any amendments) applies.

IEC 61158 (all parts), *Industrial communication networks – Fieldbus specifications*

IEC 62453-1:2009, *Field Device Tool (FDT) interface specification – Part 1: Overview and guidance*

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IEC 62453-2:2009, *Field Device Tool (FDT) interface specification – Part 2: Concepts and detailed description*

IEC/TR 62453-41:2009 *Field Device Tool (FDT) interface specification – Part 41: Object model integration profile – Common object model*

IEC 62453-303-1:2009 *Field Device Tool (FDT) interface specification – Part 303-1: Communication profile integration - IEC 61784 CP 3/1 and CP 3/2*

3 Terms, definitions, symbols, abbreviated terms and conventions

3.1 Terms and definitions

For the purpose of this document, the terms and definitions given in IEC 62453-1 and IEC 62453-2 apply.

3.2 Symbols and abbreviated terms

For the purpose of this document, the symbols and abbreviations given in IEC 62453-1, IEC 62453-2 and the following apply.

UML

Unified Modelling Language

[ISO/IEC 19501]

3.3 Conventions

3.3.1 Data type names and references to data types

The conventions for naming and referencing of data types are explained in IEC 62453-2 Clause A.1

3.3.2 Vocabulary for requirements

The following expressions are used when specifying requirements.

Usage of “shall” or “Mandatory”	No exceptions allowed.
Usage of “should” or “Recommended”	Strong recommendation. It may make sense in special exceptional cases to differ from the described behavior.
Usage of “can” or “Optional”	Function or behavior may be provided, depending on defined conditions.

4 Bus category

IEC 61784 CP 3/1 and CP3/2 protocols are identified in the attribute busCategory of BusCategory element by the identifiers, as specified in IEC 62453-303-1.

IEC 61784 CPF 3 protocols are using the identifiers in physicalLayer members within PhysicalLayer data type as specified in IEC 62453-303-1.

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5 Access to instance and device data

Used at methods:

- IDtmParameter::GetParameters()
- IDtmParameter::SetParameters()

These methods shall provide access to at least to all parameters defined in IEC 62453-303-1.

6 Protocol specific behavior

6.1 General

A DTM shall deliver its GSD information via method IDtmInformation::GetInformation() and IDtmParameter::GetParameters(). GSD information is provided in the attribute <deviceTypeInfoInformation>. Also it is required to provide a GSD file for each supported device type on the hard drive. The attribute <deviceTypeInfoInformationPath> in the DTMPParameter document specifies the location of the GSD file.

It is expected that a Profibus DTM in the attribute ‘deviceTypeInfoInformation’ is exposing exactly the GSD file which is referenced by the attribute ‘deviceTypeInfoInformationPath’.

If the GSD depends on bus settings, a DTM’s configuration or parameterization dialog could be used to change bus settings. Based on these settings, updated GSD information can be inserted in the information document. Here too the DTM has to call IFdtContainer::SaveRequest() and IDtmEvents::OnParameterChanged().

Notice that the internal device structure (<InternalTopology>) with its modules and channels has to be updated as well.

An example for documents of a DTM representing a remote I/O can be found in Annex A.

6.2 Representing modularity

6.2.1 Monolithic DTMs

Monolithic DTM's should always provide at least one <Module> element.

A monolithic DTM that represents a modular device shall provide the structure information as part of the <InternalTopology> element. The IO values of the device are represented by Process Channels, which are referenced by child elements of the <Module> elements. If any of the modules provides communication, the respective <Module> element shall reference a Communication Channel.

Example 1:

A monolithic DTM for a PROFIBUS PA device will provide the information about instantiated modules in the <InternalTopology> element. – Each instantiated module will be represented as a <Module> element. (Be aware: it is necessary to define an <InternalChannel> element for each <Module> element.)

The IO values of the modules are represented as Process Channels, which are referenced by child elements of the <Module> elements. (see Figure 2)

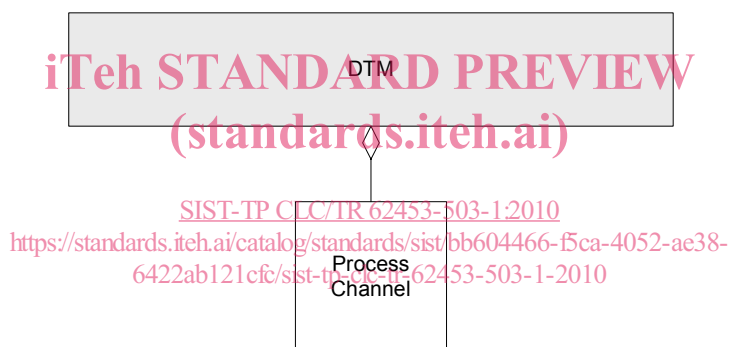


Figure 2 – Example: Device DTM

This means:

The DTM shall provide an internal topology in the parameter document to inform the frame about the internal structure of the device. The internal topology shall also include the module structure (element <Module>).

The DTM shall provide all channels in the channel collection based on the current configuration.

When the DTM changes the configuration of the process data or the module configuration the Process Channels shall be updated. This means Process Channels shall be removed/added and the parameter document shall be updated (e.g. by adding/removing <Module> elements) if necessary.

Each channel is represented by a channel reference that is child of a <Module> element in the parameter document.

Each channel object delivers a document based on the FDTProfibusChannelParameterSchema in IFdtChannel::GetChannelParameters() for the supported protocol.

Example 2:

A monolithic Gateway DTM for a remote I/O system, which requires PROFIBUS communication and has some